# JK-SMD400L PPTC DEVICES Part Number: Q/JKTD-16-400

A

JK 300L



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Terminal pad materials :Tin-Plated Nickle-copper

Terminal pad solderability : Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3.

Marking : JK300L=2920(400)

Table1 :DIMENTION(Unit : mm)

В

Model	Marking	А		В		С		D	Е
		Min.	Max.	Min.	Max.	Min.	Max	Min.	Min.
JK-SMD400L	JK300L	6.73	7.98	4.80	5.44	0.50	1.20	0.30	0.25

E

### Table2 :PERFORMANCE RATINGS:

Model	V <sub>max</sub> (Vdc)	I <sub>max</sub> (A)	I <sub>hold</sub> @25°C (A)	I <sub>trip</sub> @25°C (A)	P <sub>d</sub> Typ (W)	Maximum Time To Trip		Resistance		
						Current	Time	Ri <sub>min</sub>	Ri <sub>typ</sub>	$R1_{\text{max}}$
						(A)	(Sec)	$(\Omega)$	(Ω)	$(\Omega)$
JK-SMD400L	16.0	100	4.0	8.00	1.500	20.0	4.0	0.012	0.017	0.045

### Table3:Test Conditons and Standards

Item	Test Conditon	Standard		
Initial Resistance	25°C	$0.012{\sim}0.045\Omega$		
I <sub>H</sub>	25°C, 4.00A, 60min	No Trip		
Ttrip	25°C, 20.0A	≤4.0s		
Trip endurance	16V, 100A, 1hr	No arcing or burning		

Operating Temperature: -40°C TO 85°C Packaging: Bulk ,1500pcs per bag

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#### JK-SMD400L PPTC DEVICES Edition: A0 Part Number: Q/JKTD-16-400 Page No: 2 OF 3 F217453 Solder reflow conditions tp Critical Zone Tp r, to Tp Ramp up T lemperature TSMAX TS<sub>MIN</sub> ts Ramp down Preheat 25 t 25°C to Peak Time = **Reflow Profile Profile Feature Pb-Free Assembly** Average ramp up rate (Ts<sub>MAX</sub> to Tp) • Recommended reflow methods: IR, vapor phase 3°C/second max. Preheat oven, hot air oven, N2 environment for lead-free. • Temperature min. (Ts<sub>MIN</sub>) 150°C • Devices are not designed to be wave soldered to Temperature max. (Ts<sub>MAX</sub>) 200°C the bottom side of the board.

60-120 seconds

60-150 seconds

30 seconds max.

3°C/second max.

8 minutes max.

217°C

260°C

• Recommended maximum paste thickness is 0.25mm (0.010inch).

• Devices can be cleaned using standard industry methods and solvents.

• Soldering temprature profile meets RoHs leadfree process.

Note: All temperatures refer to topside of the package, measured on the package body surface

Time (ts<sub>MIN</sub> to ts<sub>MAX</sub>)

• Temperature (T<sub>1</sub>)

Ramp down rate

• Time (t<sub>L</sub>)

Time (tp)

Time maintained above:

Peak/Classification temperature (Tp)

Time 25°C to peak temperature

Time within 5°C of actual peak temperature

Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements

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# JK-SMD400L PPTC DEVICES Part Number: Q/JKTD-16-400 $\overrightarrow{Pb}$ $\overrightarrow{E217453}$ $\overrightarrow{Pb}$ $\overrightarrow{ROHS}$ 2.3 ± 0.1 2.3 ± 0.1

6 ± 0.

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### Solder reflow conditions

 $-15.1 \pm 0.1$ 

## Storage

The maximum ambient temperature shall not exceed  $38 \,^{\circ}$ C. Storage temperatures higher than  $38 \,^{\circ}$ C could result in the deformation of packaging materials. The maximum relative humidity recommended for storage is 60%. High humidity with high temperature can accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components. Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use. The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present

### WARNING

 $\cdot$  Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.

 $\cdot$  PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.

• Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.

· Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.

· Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.

 $\cdot$  Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices.PPTC SMD can be cleaned by standard methods.

 $\cdot$  Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profilecould negatively impact solderability performance of our devices.

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